

WHAT IS CLAIMED IS:

1. A substrate cleaning apparatus comprising:
a plurality of substrate rotating rollers for gripping the periphery of a substrate and rotating the substrate;
a cleaning roller capable of rotating and having a cleaning member which is to be brought into contact with an end face and/or a bevel face of the substrate so as to perform scrub-cleaning to the end face and/or the bevel face; and
a power transmission mechanism for transmitting a rotating force of at least one roller of the substrate rotating rollers to the cleaning roller so as to rotate the cleaning roller.
2. A substrate cleaning apparatus of claim 1, wherein the power transmission mechanism has its revolution transfer ratio set such that there would be a relative difference in velocity between a peripheral velocity of revolution of the cleaning member and a peripheral velocity of revolution of the substrate.
3. A substrate cleaning apparatus of claim 1 further comprising a cleaning nozzle for injecting a cleaning liquid against a surface of the cleaning member to be brought into contact with the substrate.
4. A substrate cleaning apparatus of claim 1 further comprising a force adjusting mechanism for adjusting an amount of pushing of the cleaning member against the end face and/or bevel face of the substrate.
5. A substrate cleaning apparatus of claim 1, wherein the cleaning roller is rotatably supported on the free end

of a swingable swing arm, wherein the swing arm is biased in the direction of bringing the cleaning member into contact with the end face and/or bevel face of the substrate.

6. A substrate cleaning apparatus of claim 1, further comprises a contact location adjusting mechanism for vertically adjusting a contact location of the cleaning member with the substrate in the height direction of the cleaning member.

7. A substrate cleaning apparatus of claim 2, further comprising a cleaning nozzle for injecting a cleaning liquid against a surface of the cleaning member to be brought into contact with the substrate.

8. A substrate cleaning apparatus of claim 2, further comprising a force adjusting mechanism for adjusting an amount of pushing of the cleaning member against the end face and/or bevel face of the substrate.

9. A substrate cleaning apparatus of claim 2, wherein the cleaning roller is rotatably supported on the free end of a swingable swing arm, wherein the swing arm is biased in the direction of bringing the cleaning member into contact with the end face and/or bevel face of the substrate.

10. A substrate cleaning apparatus of claim 2, further comprising a contact location adjusting mechanism for vertically adjusting a contact location of the cleaning member with the substrate in the height direction of the cleaning member.

11. A substrate cleaning apparatus of claim 3, further comprising a force adjusting mechanism for adjusting an amount of pushing of the cleaning member against the end face and/or bevel face of the substrate.

12. A substrate cleaning apparatus of claim 3, wherein the cleaning roller is rotatably supported on the free end of a swingable swing arm, wherein the swing arm is biased in the direction of bringing the cleaning member into contact with the end face and/or bevel face of the substrate.

13. A substrate cleaning apparatus of claim 3 further comprising a contact location adjusting mechanism for vertically adjusting a contact location of the cleaning member with the substrate in the height direction of the cleaning member.

14. A substrate cleaning apparatus of claim 4, wherein the cleaning roller is rotatably supported on the free end of a swingable swing arm, wherein the swing arm is biased in the direction of bringing the cleaning member into contact with the end face and/or bevel face of the substrate.

15. A substrate cleaning apparatus of claim 4, further comprising a contact location adjusting mechanism for vertically adjusting a contact location of the cleaning member with the substrate in the height direction of the cleaning member.

16. A substrate cleaning apparatus of claim 5, further comprising a contact location adjusting mechanism for

vertically adjusting a contact location of the cleaning member with the substrate in the height direction of the cleaning member.